

# **MICRO AND NANO FABRICATION OF TERAHERTZ WAVEGUIDE COMPONENTS**

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# **MICRO AND NANO FABRICATION OF TERAHERTZ WAVEGUIDE COMPONENTS**

by

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Submitted

in fulfilment of the requirements of the degree of Doctor of Philosophy

to the



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***This thesis work is dedicated to***

My Parents, Family and Friends

## **CERTIFICATE**

I hereby certify that the dissertation entitled “**MICRO AND NANO FABRICATION OF TERAHERTZ WAVEGUIDE COMPONENTS**” submitted by **Mr. Rakesh Kumar Bhardwaj** in fulfillment of the award of **Doctor of Philosophy** in Mechanical Engineering Department of the Indian Institute of Technology Delhi is an authentic record of the investigations carried out by him under my guidance and supervision. The presented work has fulfilled the requirement for the submission of this thesis and has reached the required criterion to the best of my knowledge and belief.

The research work has not been submitted previously for the award of any degree of any other university.

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## Abstract

The demand of high-speed wireless communication has increased, which need the data rate of the order of Terabyte per second (Tbps) in near future. Terahertz (THz) band communication is a key wireless communication technology to satisfy this future demand. This will also reduce the spectrum scarcity and capacity limitation of current wireless systems. Micro fabricated folded waveguides are potential compact source of wide band and high-power terahertz radiation.

This study primarily focuses on machining technology for THz waveguide components requiring ultra-high precision micro machining. Rectangular waveguides especially folded waveguides are even more difficult to manufacture using conventional machining techniques due to their small size and very tight tolerances. The criticalities in micromachining of Terahertz waveguide Components starting from 100GHz to 1100 GHz been developed mechanically in this research work. Free cutting Brass IS 319-H<sub>2</sub> and AL Alloy IS:736 24345 WP were used as work materials due to its electrical and mechanical properties. Waveguide size as small as 0.254x0.127 mm ( 254x127  $\mu\text{m}$ ) was micro machined within  $\pm 3\text{-}5$   $\mu\text{m}$  linear tolerances, surface roughness of the order of 0.045  $\mu\text{m}$  Ra and flatness less than 0.3  $\mu\text{m}$  ( $< \lambda/2$ ). The split top and bottom blocks of the waveguide were aligned by dowel pins which matched within a tolerance of  $\pm 5$   $\mu\text{m}$ . The perpendicularity and parallelism were maintained within  $\pm 5$   $\mu\text{m}$  tolerance as per IS:8000, 1975. This work explored and established the application of micro milling as reasonably suitable for the THz waveguides followed by ultrasonic cleaning. Waveguide above 1.1 THz having waveguide size as small as 75 $\mu\text{m}$ x 37.5 $\mu\text{m}$  were also realized using femto second LASER within nanometer level accuracies. Measurements of folded waveguide at 0.22THz waveguide losses were close to simulated values.

Keywords: Terahertz (THz); Waveguide; folded waveguide; Linear Tolerance; Surface roughness; Micromachining; Femto second Laser; S-Parameters; Geometrical Tolerances; Lapping; Dowel Pin.

## सार

हाई-स्पीड वायरलेस कम्युनिकेशन की मांग बढ़ गई है, जिसे निकट भविष्य में टेराबाइट प्रति सेकंड (Tbps) के ऑर्डर की डेटा दर की आवश्यकता है। टेराहर्ट्ज (THz) बैंड संचार भविष्य की इस मांग को पूरा करने के लिए एक प्रमुख वायरलेस संचार तकनीक है। यह स्पेक्ट्रम की कमी और मौजूदा वायरलेस सिस्टम की क्षमता सीमा को भी कम करेगा। माइक्रो फ़ैब्रिकेटेड फोल्डेड वेवगाइड वाइड बैंड और हाई-पावर टेराहर्ट्ज विकिरण के संभावित कॉम्पैक्ट स्रोत हैं।

यह अध्ययन मुख्य रूप से अल्ट्रा-उच्च परिशुद्धता माइक्रो मशीनिंग की आवश्यकता वाले THz वेवगाइड घटकों के लिए मशीनिंग तकनीक पर केंद्रित है। आयताकार वेवगाइड विशेष रूप से मुड़े हुए वेवगाइड अपने छोटे आकार और बहुत सख्त सहनशीलता के कारण पारंपरिक मशीनिंग तकनीकों का उपयोग करके निर्माण करना और भी कठिन होता है। इस शोध कार्य में १०० गीगाहर्ट्ज से ११०० गीगाहर्ट्ज तक के टेराहर्ट्ज वेवगाइड घटकों के माइक्रोमशीनिंग में महत्वपूर्णताओं को यांत्रिक रूप से विकसित किया गया है। फ्री कटिंग ब्रास IS 319-H2 और AL अलॉय IS:736 24345 WP को इसके विद्युत और यांत्रिक गुणों के कारण कार्य सामग्री के रूप में उपयोग किया गया था। वेवगाइड का आकार  $0.254 \times 0.127$  मिमी जितना छोटा था,  $\pm 3-5$  माइक्रोन रैखिक सहिष्णुता, 45 नैनो मीटर Ra के क्रम की सतह खुरदरापन और  $0.3 \mu\text{m} (< \lambda/2)$  से कम समतलता के भीतर सूक्ष्म मशीनीकृत था। वेवगाइड के विभाजित शीर्ष और निचले ब्लॉक को डॉवेल पिन द्वारा संरेखित किया गया था जो  $\pm 5$  माइक्रोन की सहनशीलता के भीतर मेल खाता था। लंबवतता और समानता को IS:8000, 1975 के अनुसार  $\pm 5$  माइक्रोन सहिष्णुता के भीतर बनाए रखा गया था। इस कार्य ने माइक्रो मिलिंग के अनुप्रयोग को टेराहर्ट्ज वेवगाइड के लिए उपयुक्त रूप से उपयुक्त के रूप में खोजा और स्थापित किया जिसके बाद अल्ट्रासोनिक सफाई हुई। 1.1 THz से ऊपर के वेवगाइड, जिनका वेवगाइड आकार  $75 \mu\text{m} \times 37.5 \mu\text{m}$  जितना छोटा है, को नैनोमीटर स्तर की सटीकता के भीतर फेम्टो सेकंड लेजर का उपयोग करके महसूस किया गया। 0.22 THz फोल्डेड वेवगाइड की माप सिमुलेटेड मूल्यों के करीब थी।

कीवर्ड: टेराहर्ट्ज (THz); वेवगाइड; मुड़ा हुआ वेवगाइड; रैखिक सहिष्णुता; सतह खुरदरापन; सूक्ष्म मशीनिंग; फेम्टो सेकंड लेजर; एस-पैरामीटर; ज्यामितीय सहिष्णुता; लैपिंग; मेख पिन

## Table of Contents

<b>Chapter 1: Introduction .....</b>	<b>1</b>
<b>1.1 Background .....</b>	<b>1</b>
<b>1.2 Introduction to Terahertz waves and Terahertz Technology .....</b>	<b>4</b>
1.2.1 EM waves and their propagation.....	4
1.2.2 EM Spectrum .....	5
<b>1.3 Introduction to Waveguides.....</b>	<b>6</b>
1.3.1 Modes of propagation in a Waveguide.....	8
<b>1.4 Characteristics of Waveguide .....</b>	<b>9</b>
1.4.1 Advantages of Waveguides.....	9
1.4.2 Types of Waveguides .....	10
<b>1.5 Waveguide Impedance and Characteristic Impedance Matching .....</b>	<b>10</b>
1.5.1 Waveguide impedance .....	10
1.5.2 Waveguide impedance and reflection coefficient .....	11
1.5.3 Waveguide Cut-off Frequency .....	11
1.5.4 Waveguide cut-off frequency background.....	11
1.5.5 Waveguide cut-off frequency for rectangular waveguide.....	11
<b>1.6 Rectangular waveguide modes.....</b>	<b>12</b>
1.6.1 Parameters of a Waveguide.....	12
<b>1.7 Frequency Bands and designations .....</b>	<b>12</b>
<b>1.8 Worldwide status of Terahertz Technology .....</b>	<b>13</b>
<b>1.9 Status of Terahertz Technology in India .....</b>	<b>14</b>

<b>1.10 Micromachining of Waveguide.....</b>	<b>17</b>
1.10.1    Tool based Micromachining/ Mechanical micromachining .....	18
1.10.2    MASK based Micromachining / Silicon micromachining .....	18
1.10.3    Micro molding .....	19
1.10.4    Laser Micromachining .....	20
<b>Chapter 2: Literature Review .....</b>	<b>21</b>
<b>2.1 Historical Background.....</b>	<b>21</b>
2.1.1    EM waves and their propagation in waveguides.....	22
<b>2.2 Terahertz Technology .....</b>	<b>23</b>
2.2.1    THz applications at the nanoscale .....	25
2.2.2    THz Applications at the microscale .....	25
2.2.3    THz Applications at the macro scale.....	25
<b>2.3 Terahertz versus Millimeter-wave and Infrared .....</b>	<b>25</b>
<b>2.4 Mechanical Engineering Challenges in THz Technology .....</b>	<b>27</b>
2.4.1    Mechanical Design Methodology .....	28
2.4.2    Material Selection .....	28
2.4.3    Waveguide Interface Standards.....	29
2.4.4    Misalignments in Waveguides .....	29
2.4.5    Tolerances .....	31
<b>2.5 Micromachining .....</b>	<b>33</b>
2.5.1    Micro milling .....	34
2.5.2    Femtosecond micro machining .....	37
<b>2.6 Mechanical Measurements.....</b>	<b>37</b>

<b>2.7 Residual stresses and their measurements .....</b>	<b>38</b>
<b>2.8 Research Gap .....</b>	<b>39</b>
<b>2.9 Motivation.....</b>	<b>40</b>
<b>2.10 Research Objective .....</b>	<b>41</b>
<b>Chapter 3: Material Selection and Properties .....</b>	<b>42</b>
<b>3.1 Materials selection and design of waveguide.....</b>	<b>42</b>
3.1.1 Free cutting brass IS 319-H <sub>2</sub> .....	42
3.1.3 Oxygen-Free High conductive Copper (OFHC) .....	44
3.1.4 Mg Alloy AZ 91 .....	45
3.1.5 Silicon family .....	46
3.1.6 Graphene on Silicon.....	47
3.1.7 Polymer materials.....	47
<b>3.2 Importance of Linear and Geometrical Tolerances in Terahertz component .....</b>	<b>47</b>
3.2.1 Linear Tolerances.....	47
3.2.2 Unilateral Tolerance.....	48
3.2.3 Bilateral Tolerance .....	48
3.2.4 Geometrical Tolerances.....	48
3.2.5 Importance of Geometrical tolerances in context of THz waveguides .....	55
<b>3.3 Residual Stresses during micromachining and their measurement.....</b>	<b>60</b>
3.3.1 Residual Stresses .....	60
3.3.2 Effects of residual stresses .....	61
3.3.3 Effect of Residual Stresses on Waveguide (WG) Configuration .....	62
<b>Chapter 4: Micro Machining of Terahertz Waveguide Components.....</b>	<b>64</b>

<b>4.1 History of Micro Manufacturing and Micro Milling.....</b>	<b>64</b>
<b>4.2 Micro milling .....</b>	<b>65</b>
4.2.1 Micromachining Setup .....	67
4.2.2 Preparation of Samples.....	68
4.2.3 Touch-Trigger Probing and Laser Measuring Systems.....	69
<b>4.5 Cutting mechanisms.....</b>	<b>72</b>
<b>4.6 Machining strategies to minimize surface roughness .....</b>	<b>73</b>
4.7.1 Analysis of Variance (ANOVA).....	76
<b>4.8 Laser Micromachining .....</b>	<b>79</b>
4.8.1 Parameters of laser Machining.....	79
<b>4.9 CW Fiber Laser Cutting .....</b>	<b>79</b>
<b>4.10 Nanosecond Laser Cutting.....</b>	<b>80</b>
<b>4.11 Femtosecond laser Cutting and Process Parameters.....</b>	<b>81</b>
<b>Chapter 5: Mechanical Measurements.....</b>	<b>84</b>
<b>5.1 Measuring Instruments for Linear and Geometrical Tolerances .....</b>	<b>84</b>
5.1.1 Multi-Sensor Measurement Station.....	84
5.1.2 Galileo Starrett 3D vision system.....	85
5.1.3 Surface Roughness Tester .....	85
5.1.4 Optical Surface profiler .....	85
5.1.5 Surface Flatness Checking .....	87
<b>5.2 Measurement of Linear and Geometrical Tolerances.....</b>	<b>88</b>
5.2.1 Measurement of Surface Roughness .....	89

5.2.2	Measurement of Straightness .....	90
5.2.3	Measurement of Perpendicularity .....	91
5.2.4	Measurement of Parallelism.....	91
5.2.5	Measurement of Circularity .....	92
5.2.6	Measurement of Dowel Pin Diameter.....	92
5.2.7	Measurement of Residual Stresses .....	93
5.2.8	X ray Diffractometer (XRD).....	94
<b>5.3 Study of Surface Topography .....</b>		<b>99</b>
<b>Chapter 6: Electrical and Transmission Measurements.....</b>		<b>105</b>
<b>6.1 Network Analyzer Features (KEYSIGHT N5222A) .....</b>		<b>105</b>
6.1.1	Transmission modes in waveguide .....	107
<b>6.2 Losses in Waveguide.....</b>		<b>108</b>
6.2.1	Attenuation.....	108
6.2.2	Absorption.....	108
6.2.3	Scattering.....	108
6.2.4	Mie scattering (MS) .....	108
6.2.5	Bends.....	108
6.2.6	Micro bending .....	109
<b>6.3 Strategies of minimizing waveguide losses .....</b>		<b>110</b>
6.3.1	Losses at the bends.....	110
6.3.2	Propagation Loss.....	110
<b>6.4 S parameters measurement.....</b>		<b>110</b>
6.4.1	Waveguide Loss ( $S_{21}$ -Parameter) and Dispersion measurements .....	112
6.4.2	Dispersion Measurements .....	113

<b>Chapter 7: Results and Discussion</b> .....	<b>118</b>
<b>7.1 Results in context of the research objective</b> .....	<b>118</b>
7.1.1 Mechanical Parameters Achieved against the required Parameters .....	118
<b>7.2 Effect of Residual Stresses on Transmission losses</b> .....	<b>121</b>
<b>7.3 Topography Improvement inside Waveguide</b> .....	<b>122</b>
<b>7.4 Suitable Manufacturing Strategies for different Frequency Bands</b> .....	<b>122</b>
<b>Chapter 8: Discussion and Further Scope</b> .....	<b>124</b>
<b>8.1 Conclusions</b> .....	<b>124</b>
<b>8.2 Further Scope of Study</b> .....	<b>124</b>
<b>References</b> .....	<b>126</b>

## List of Figures

Figure 1.1: Atmospheric transmission in the THz region at various locations and altitudes for given precipitable water vapour pressure (mm) (a) 0-500GHz and (b) 500-2000GHz [2].	2
Figure 1.2: Wireless Roadmap Outlook up to the year 2035 [23][19].	4
Figure 1.3: Spectrum of electromagnetic radiation.	5
Figure 1.4: (a) hollow metal rectangular waveguide, (b) Waveguide bend, (c) Cross section of a waveguide with long dimension ‘a’ and short dimension ‘b’[67]-[70].	6
Figure 1.5: (a) Coaxial cable adapters, (b) Types of waveguide cross sections [67]-[70].	7
Figure 1.6: Propagation of an electromagnetic wave in the z-direction [25], [26].	8
Figure 1.7: Status of Terahertz technology and systems, © Tematys [28].	14
Figure 1.8: Time line of technology implementation to realize viable THz communication in India.	16
Figure 2.1 (a) 100% THz view of the painting ; (b) the same painting with 50% THz visible (c) Image of Goya’s painting, The Sacrifice to Vesta, [60].	22
Figure 2.2: Applications of Terahertz Technology [28].	24
Figure 2.3: The Attenuation impact of different environmental effects at various frequencies [78].	26
Figure 2.4: Standardization journey of THz technology	29
Figure 2.5, Effect of misalignment of waveguide ports on power losses	30
Figure 2.6: Sketch of the recommended waveguide interface from WR-10 to WR-1	33
Figure 3.1: Typical cross-section of a rectangular waveguide	48
Figure 3.2: Effect of tolerances on the cross-section of the waveguide	48
Figure 3.3: Sketch of Straightness, IS standard 8000 (Part 1) :1985	49

Figure 3.4: Sketch of flatness, IS standard 8000 (Part 1) :1985 .....	50
Figure 3.5: Sketch of Circularity, IS standard 8000 (Part 1) :1985 .....	50
Figure 3.6: Sketch of cylindricity, IS standard 8000 (Part 1):1985 .....	51
Figure 3.7: Sketch of profile, IS standard 8000 (Part 1):1985.....	51
Figure 3.8 , Sketch of Perpendicularity of line w.r.t surface, IS standard 8000 (Part 1):1985.....	52
Figure 3.9: Sketch of Perpendicularity of surface w.r.t line, IS standard 8000 (Part 1):1985.....	52
Figure 3.10: Sketch of Perpendicularity between two surfaces, IS standard 8000 (Part 1):1985.	52
Figure 3.11: Sketch of Parallelism between two lines, IS standard 8000 (Part 1) :1985.....	53
Figure 3.12: Sketch of Parallelism between surface and datum, IS standard 8000 (Part 1):1985	53
Figure 3.13: Sketch of angularity, IS standard 8000 (Part 1) :1985 .....	54
Figure 3.14: Sketch of positional tolerance. IS standard 8000 (Part 1) :1985 .....	54
Figure 3.15: Sketch of Concentricity, IS standard 8000 (Part 1) :1985.....	55
Figure 3.16: Sketch of Run out, IS standard 8000 (Part 1) :1985.....	55
Figure 3.17: (a) Power absorption ratio for different RMS height For Copper. (b) Power absorption ratio for different RMS height For Aluminum [112].....	56
Figure 3.18: Reflectivity versus frequency for different rough samples. (a) for Copper and (b) for Aluminum [195].....	57
Figure 3.19: Normalized power spectral density of Aluminum and Copper for different rough height. (a) for Aluminum and (b) for Copper [195].....	57
Figure 3.20: Sketch of the recommended waveguide interface from WR-10 to WR-1[27].....	58
Figure 3.21: (a) Dimensions and tolerances of Dowel pins and pin holes, (b) The miniature interface.[27].....	59

Figure 3.22: (a) Effect of residual stresses on the cross-section a x b of the W/G, (b) effect of corner radius, (c) effect of misalignment in “a”, (d) misalignment in “b”, (e) Twisting of W/G cross section and (f) configuration of folded W/G .....	62
Figure 4.1: Relative accuracy and object size, CHENG et al. [123].....	64
Figure 4.2: (a) Kern Micro milling, (b) Different systems of micro milling machine (c) Polymeric concrete construction, (d) Centering microscope [120] .....	67
Figure 4.3: 3D touch probe, RENISHAW OMP .....	70
Figure 4.4: Laser Controlled, in-process tool management system. ....	71
Figure 4.5: Illustration showing the size effect in (a) macro and (b) micro-cutting [126]. ....	73
Figure 4.6: Generic geometry of micro milling cutters containing a head, neck, and shank, and the magnification of tool heads from (b) front and (c) side views, [135], (d) SEM Image of cutter having a diameter of 70 $\mu$ m .....	73
Figure 4.7: (a) Mean of S/N ratios versus factor and (b) Main effect plot .....	78
Figure 4.8: (a) SEM Image of sample cut on CW fiber laser [Free cutting Brass IS: 319 H <sub>2</sub> ] and (b) SEM Image for [Al Alloy IS: 736 24345WP] .....	80
Figure 4.9: Surface Roughness of Nano laser cut Free cutting Brass IS: 319 H <sub>2</sub> sample. ....	81
Figure 4.10:(a) Femtosecond laser cutting Machine (Star cut tube), (b) Flat cutting attachment; (c) Samples of Al Alloy, (d)Free cutting Brass, (e) samples of Mg Alloy and (f) samples of 99% pure Copper.....	83
Figure 5.1: Multi-sensor measurement station and its features [Curtsy CAME, DEAL, DRDO]	84
Figure 5.2: Starrett 3D vision system and its features [Curtsy CAME, DEAL, DRDO] .....	85
Figure 5.4: (a) Interferometer, (b) sample holder and sample [Curtsy Optical fabrication facility, IRDE, DRDO].....	86

<i>Figure 5.5: (a) Optical Surface profiler and Technical Features of Contour GT-X optical profiler. Curtsy CAME, DEAL, DRDO.....</i>	87
<i>Figure 5.6: Surface Flatness checking setup and its features Curtsy CAME, DEAL, DRDO.....</i>	88
<i>Figure 5.7: Micro machined Components at THz frequency band .....</i>	89
<i>Figure 5.8: (a) Surface Profiler, (b) Sample placed under the lens, (c) Surface Roughness achieved inside WG.....</i>	90
<i>Figure 5.9: (a) Straightness of waveguide edge, (b) Measured Value .....</i>	91
<i>Figure 5.10: (a) Perpendicularity of waveguide edges, (b) Measured Value .....</i>	91
<i>Figure 5.11: Measurement of parallelism between two sides of W/G.....</i>	92
<i>Figure 5.12: (a) Starrett Measuring station, (b) Measured of Circularity, (c) Circularity value</i>	92
<i>Figure 5.13: (a) Laser Micrometer, (b) V Blocks for keeping the measurement sample like dowel pin .....</i>	93
<i>Figure 5.14: Diffraction of X-rays by a Crystal Lattice (adapted from [208], [200]).....</i>	94
<i>Figure 5.15: (a) Rigaku smart lab x-ray Diffractometer with Co-K<math>\alpha</math> (<math>\lambda=1.79 \text{ \AA}</math>) with radiation at 40 KV and 30 mA, (b) Sample placement details.....</i>	95
<i>Figure 5.16: (a) Al Alloy Straight and Folded W/G, (b) Variation of Intensity w.r.t. Theta for Al Alloy W/G.....</i>	97
<i>Figure 5.17: (a) Brass straight and folded waveguide, (b) Variation of Intensity w.r.t. Theta for free cutting brass.....</i>	98
<i>Figure 5.18: (a) 2 Theta Vs Sin (<math>\Psi</math>)<sup>2</sup> for Al Alloy W/G, (b) 2 Theta Vs Sin (<math>\Psi</math>)<sup>2</sup> for Free Cutting Brass W/G .....</i>	98
<i>Figure 5.19: SEM image of micro cutter (a) Side view, (b) Top view &amp; (c) Zoomed view [201].</i>	100

Figure 5.20: Tool tip trajectory at different spindle speeds [201] .....	100
Figure 5.21: Surface topography of micro slot milled region at different cutter length showing, feed marks, plastic flow lines and metal debris [201], [209], [210]. .....	101
<i>Figure 5.22 (a) Samples of free cutting brass, (b)Topography of Brass sample without machining (SEM) (c) Topography of Brass Waveguide after micro machining at 0.330 THz (d) Topography of Brass Waveguide after micro machining at 0.625 THz (e) Topography of Brass Waveguide after micro machining at 1.1 THz (f) SEM image of Folded waveguide after machining .....</i>	<i>103</i>
<i>Figure 5.23: (a) AL Alloy samples, (b) Topography of sample without machining (SEM), (c) Topography of AL Alloy Waveguide after micromachining at 0.330 THz (d) Topography of AL ALLOY Waveguide after micromachining at 0.625 THz (e) Topography of AL ALLOY Waveguide after micromachining at 1.1 THz (f) Folded waveguide of Al Alloy and (g) SEM Image of FWS. ....</i>	<i>105</i>
Figure 6.1: Network Analyzer .....	106
Figure 6.2: (a) Vertically polarized electromagnetic wave, (b) A typical rectangular Q-band ..	107
Figure 6.3: Bend Losses (leaky modes) at the waveguide bends – macrobends .....	109
Figure 6.4: Micro bending Losses (leaky modes) as a result of imperfections in the waveguide structure – micro bends. ....	109
Figure 6.5: Network analyser setup for measurements.....	111
Figure 6.6: Waveguide holder for measurement.....	113
Figure 6.7 Assembly of FWS and dispersion measurements using PNA N5222A .....	113
Figure 6.8: Comparison of dispersion characteristics with measurements.....	115
Figure 6.9: Insertion loss measurements.....	116

Figure 6.10: Measurement of return loss ..... 117

Figure 7.1: SEM image of folded waveguide; (b) SEM Image after Ultrasonic cleaning..... 121

Figure 8.1: Concept of planar technology (a) planar waveguide; (b) Discrete Components  
[Curtsy CAME, DEAL, DRDO]..... 124

## List of Tables

Table 1.1: Current and proposed wave guide bands. ....	13
Table 1.2: Indian research geared towards the realization of THz communication .....	15
Table 5.1: Measured waveguide sizes, linear and geometrical tolerances .....	89
Table 5.2: Range of residual stresses and the corresponding optimum cutting Parameters .....	98
Table 6.1: Mechanical parameters of folded waveguide structure .....	112
Table 6.2: Measurement of folded waveguide resonances .....	114